



# Electronic

# BALVER ZINN®

## Technical Data Sheet

### BALVER ZINN SOLDERPASTE

### RMA H-1 FDQ

### SN100C® (SnCu0,7Ni)

#### General information

**BALVER ZINN SOLDER PASTE RMA H-1 FDQ SN100C®** is a lead-free No-Clean solder paste based on **SN100C®** for air or nitrogen reflow applications. The specially flux composition of **RMA H-1 FDQ SN100C®** gives excellent print and reflow characteristics with **SN100C®**. The soldering residues of **BALVER ZINN SOLDER PASTE RMA H-1 FDQ SN100C®** are concentrated around the pad. **BALVER ZINN SOLDER PASTE RMA H-1 FDQ SN100C®** is a No-Clean formulation. The residues can remain on the board after reflow and will not interfere with in-circuit test. The paste flux system of **BALVER ZINN SOLDER PASTE RMA H-1 FDQ SN100C®** shows long tack life and long stencil life. The paste flux compositions enables reflow profiles with a peak temperature of 240°C – 250°C and enables a wide process window with lead-free solders. We recommend a temperature of 240°C for vapour phase soldering. **BALVER ZINN SOLDER PASTE RMA H-1 FDQ SN100C®** is available as a licensed lead-free alloy. SN100C-SnCu0,7Ni (EU 0985486; JPN 3152945; US 6180055).

\***BALVER ZINN SOLDER PASTE RMA H-1 FDQ SN100C®** does not contain hazardous substances beyond the limits prescribed by EU Directive 2011/65/EU ("RoHS II").

Technical information and further Technical Data Sheets can be found on our website ([www.BALVERZINN.com](http://www.BALVERZINN.com)). You can also obtain all information and documents directly from **BALVER ZINN**.

#### BALVER ZINN Production Programme

The **BALVER ZINN** production programme also includes solder pastes, flux and solder wires. Beside the **SN100C®** product family, **BALVER ZINN** offers additional unpatented and patented solder alloys for wave soldering, reflow and rework.

#### Product Properties

- Flux classified according to J-STD-004 as: **ROL1**
- Paste classified according to EN 61190 -1-2: **ROL1**
- RoHS compliant\*
- Compatible with RoHS conform solder masks
- Bright and shiny solder joints with SN100C
- Long tack time
- Excellent print results with 16 and 20 mils pitch

#### Physical and Chemical Properties of flux RMA H-1 FDQ

<b>Metal content:</b>	87.5%
<b>Viscosity:</b> Brookfield viscometer @ 10 rpm and 25°C	330Pas
<b>Initial Tackiness:</b> J-STD-004, IPC-TM-650, Method 2.4.44	100gf
<b>Slump Test:</b> JIS-Z-3284 Appendix 7; Appendix 8	pass
<b>Solder Ball Test:</b> JIS-Z-3284 Appendix 11	pass
<b>Wetting Test:</b> JIS-Z-3284 Appendix 10	pass
<b>Copper Plate Corrosion:</b> JIS-Z-3197 6.6.1	pass
<b>SIR, IPC:</b> J-STD-004, IPC-TM-650, Method 2.6.3.3	pass

**Standard application:**  
87.5% Metal for dispensing

**BALVER ZINN SOLDER PASTE RMA H-1 FDQ** is available in SN100C® (SnCu0,7Ni) lead-free alloy. Type 3 powder from 45 – 20 micron for fine pitch applications.

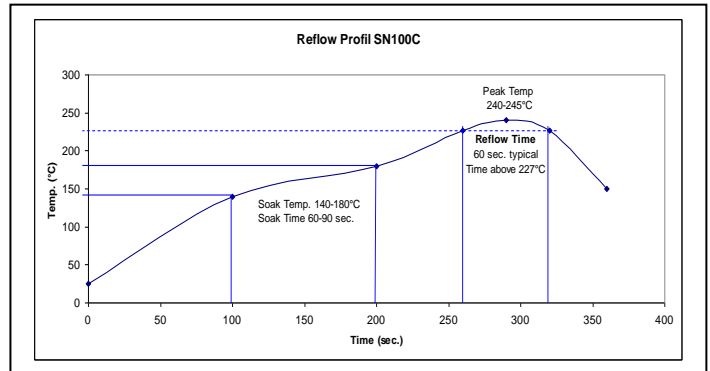
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### Recommended Reflow Profile:

The recommended reflow profile for **BALVER ZINN SOLDER PASTE RMA H-1 FDQ SN100C®** offers a wide process window allowing adjustment to suit component board loadings. The illustrated profile is based on a full convection reflow system.



### Printing Parameters:

DEK ProFlow and MPM Pumphead approved

Squeegee Blade	Stainless steel
Squeegee Speed	Capable of a max. printing speed of 150mm/sec
Stencil Material	Stainless steel
Temperature/Humidity	Optimal conditions are 21 – 25°C and 35 – 65% humidity.

### Cleaning:

**BALVER ZINN SOLDER PASTE RMA H-1 FDQ SN100C®** is a No-Clean formulation, the residues left on the board are non-conductive and non-corrosive and do not require removal in most applications. Although it is a No-Clean formulation, the residues can be easily removed with a variety of cleaning agents used in automated cleaning systems.

### Delivery sizes:

Syringe/Cartridges: 5cc, 10cc, 30cc, 60cc, 120cc

### Storage and shelf life:

It is recommended that **BALVER ZINN SOLDER PASTE RMA H-1 FDQ SN100C®** is stored in clean dry conditions with temperature 5 – 10°C to maintain consistent reflow and print characteristics. **BALVER ZINN SOLDER PASTE RMA H-1 FDQ SN100C®** should be equalized to room temperature prior to printing (minimum 8 hours). Do not use excessive heating. The time of storage in the original packaging at a temperature of 5 – 10°C amounts to 6 month in doses and 4 month in syringes or cartridges.

### Safety Advice

Before use please refer to the appropriate Safety Data Sheet.

Although the information in this data sheet is considered accurate, the measured values do not represent assured properties or delivery specifications. Because of the wide range of potential materials and applications, and with respect to possible protective rights and third parties, Balver Zinn Josef Jost GmbH & Co. KG **cannot** accept any liability.

### OUR GLOBAL DISTRIBUTION NETWORK

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